



Material Content Data Sheet



Sales Product Name		TLS810A1LD V50		Issued		20. July 2018		
MA#		MA001829504						
Package		PG-TSON-10-2		Weight*		31.70 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.996	3.14	3.14	31416	31416
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		105	
	non noble metal	zinc	7440-66-6	0.013	0.04		418	
	non noble metal	iron	7439-89-6	0.265	0.84		8369	
wire	non noble metal	copper	7440-50-8	10.773	33.98	34.87	339808	348700
	non noble metal	copper	7440-50-8	0.017	0.05	0.05	546	546
	encapsulation	organic material	carbon black	1333-86-4	0.038	0.12		1185
encapsulation	plastics	epoxy resin	-	1.935	6.10		61045	
	inorganic material	silicondioxide	60676-86-0	16.816	53.06	59.28	530443	592673
leadfinish	non noble metal	tin	7440-31-5	0.370	1.17	1.17	11674	11674
plating	noble metal	silver	7440-22-4	0.064	0.20	0.20	2027	2027
glue	plastics	epoxy resin	-	0.103	0.32		3241	
	noble metal	silver	7440-22-4	0.308	0.97	1.29	9723	12964
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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